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## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

# **CONVEYING PARTY DATA**

Name	Execution Date
YOUNG HAK JANG	12/12/2013
YOUNG HO HAN	12/12/2013
WOOMIN JUNG	12/12/2013

#### **RECEIVING PARTY DATA**

Name:	HYUNDAI MOTOR COMPANY	
Street Address: 12, HEOLLEUNG-RO, SEOCHO-GU		
City:	r. SEOUL	
State/Country: KOREA, REPUBLIC OF		

#### PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	14140428	

## CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	060944-6174-US	
NAME OF SUBMITTER:	LINDA LIM	
Signature:	/Linda Lim/	
Date:	12/26/2013	

Total Attachments: 2

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PATENT REEL: 031848 FRAME: 0208

# ASSIGNMENT (Joint Inventors)

WHE	CREAS, the undersigned,		
(1) <b>JANG, Y</b>	OUNG HAK resident of 402, Palaceville, 398-9, Yangjae 2-dong, Scocho-gu, Scoul,		
Korea	DUNG HO resident of 484-1, Sagang-ri, Songsan-myeon, Hwaseong-si, Gyeonggi-do,		
(2) HAN, IV Korea	JONG HO resident of 484-1, Sagang-11, Songsan-in-Jeon, Hwaseong Si, Oyeongg, do,		
(3) JUNG, V	VOOMIN resident of 1901-1602, Ggumdongsan Apt., Sang-dong, Wonmi-gu, Bucheon-si,		
Gyeonggi-de	o, Korea		
(hereinafter to	ermed "Inventor"), respectively, have invented certain new and useful improvements in MOLD FOR		
MAKING S	OUND-ABSORBING DUCT AND SOUND-ABSORBING DUCT USING THE SAME		
and executed	therefore an application for Letters Patent of the United States and		
	and the first term of the firs		
	bearing U.S. Patent Application No and filed on		

WHEREAS, HYUNDAI MOTOR COMPANY, a corporation of the State of Republic of Korea, having a place of business at 12. Heolleung-ro. Seocho-gu. Seoul, Republic of Korea (hereinafter termed "Assignee"), are desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventor (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventor to have been received in full from said Assignee:

- 1. Said Inventor do hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a division, substitution, or continuation of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.
- 2. Said Inventor do hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventor shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including

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without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, nfringement actions and court actions; provided, however, that the expense incurred by said Inventor in providing such cooperation shall be paid for by said Assignee.

- 3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventor, their respective heirs, legal representatives and assigns.
- 4. Said Inventor do hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Inventor have executed and delivered this instrument to said Assignee as follows:

Date:	2013 - 12 - 12	(1)	JANG, YOUNG HAK
Date:	2013 - 12 - 12	(2)	HAN, YOUNG HO
	2013-12-12	(3)	JUNG, WOOMIN

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**RECORDED: 12/26/2013**